

Hiner-pack® MVWS Canister 100 mm

*Vertical stacking shipper with cassette,
bottom, and top for wafer protection*

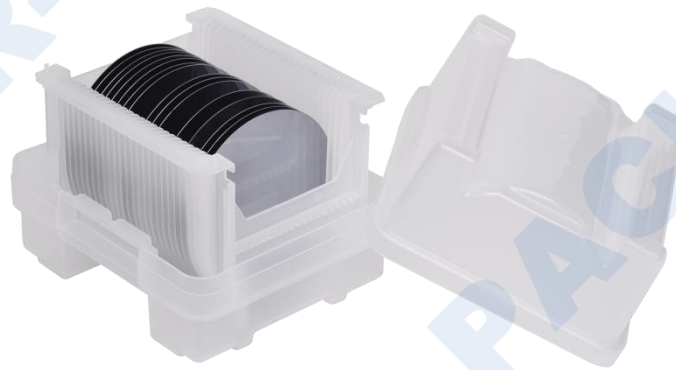
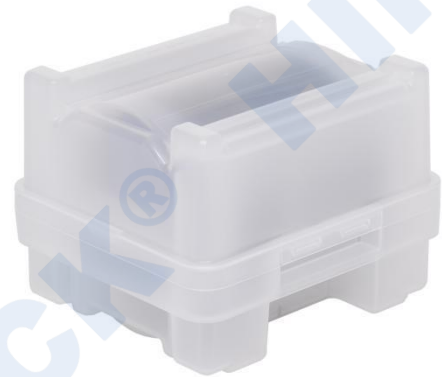
Designed for secure highly sensitive wafer transport, this vertical wafer shipper combines a bottom housing, a precision wafer cassette, and a locking top cover. The three-in-one construction stores up to 25 wafers in a stable vertical position, protecting edges from chipping during shipment. Integrated springs or alignment in the top cover hold wafers in place, preventing vibration, rotation, and misalignment. With its standardized cassette footprint, this wafer shipper works with automated load ports, transfer robots, and semiconductor storage systems. Constructed from ultra-clean polypropylene, it delivers low ionic contamination and minimal outgassing, meeting the strictest cleanroom wafer packaging requirements. Reference Materials

SPECIFICATIONS

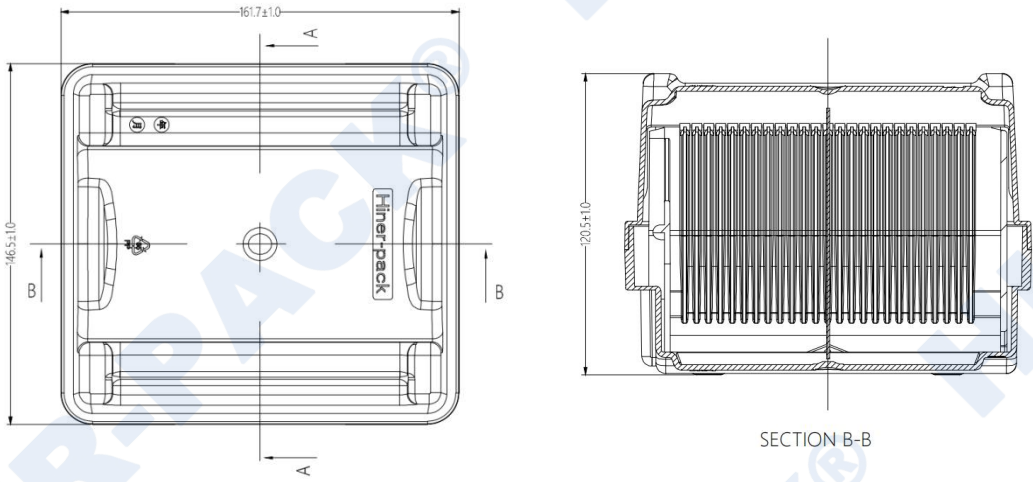
- 161.7 mm L × 146.5 mm W × 120.5 mm H (6.37" × 5.77" × 4.74")
- Maximum load capacity is 25 pieces
- Sold in full case quantity (48)

FEATURES & BENEFITS

- Made from low-particle/ionic/outgassing material
- Three-piece design includes bottom, cassette, and top
- Springs or alignment features inside the upper cover prevent wafer movement during handling
- Compatible with automation load ports and standard cassette handling tools



DIMENSION



BASIC INFORMATION

Part Number	Collocation Reference	Wafer Size
MVWS-4/25-NP-C	Bottom+Cassette+Top	100 mm

REFERENCE ILLUSTRATION



The above illustration is for reference only. Please refer to the actual product for accuracy.

TECHNICAL DATA

PROPERTY	TEST METHOD	RATED VALUES
Density	ISO 1183	0.9 g/cm ³
Melt Index	ISO 1133	15 g/10min
Melting Point	DSC	146°C
Distortion Temperature	ISO 75	95°C
Vicat softening temperature	ISO 306	125°C
Tensile Strength at Yield	ISO 527	280 kg/m ²
Tensile Elongation at Break	ISO 527	300 %
Rockwell hardness R scale	ISO 2039	98
Tensile Strain at Break	ISO 527-2 (50mm/min)	10 %
Flexural Modulus	ISO 178	10500 kg/m ²
Flow Shrinkage	FPC Method	1.3~1.7 %
LZOD Impact Strength	23°C	6 kg.cm/cm
	-20°C	--- notch

The information on technical data included in this document is based on our experience to date, and we believe it to be reliable. Data is obtained from specimens molded under controlled conditions from representative samples of the compound described. Properties may be affected by the molding techniques and by the size and shape of the item molded. We cannot guarantee favorable results and no assurances can be implied that all molded articles have the sample properties as those listed.



Hiner-pack®

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